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(54) **WIRING BOARD, ELECTRONIC DEVICE,
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ABSTRACT

A wiring board including a component mounting portion with an increased strength is provided. In addition, an electronic device and an electronic module with high reliabilities are provided. The wiring board includes a base having a first face and a conductor positioned on the first face. The conductor has a region in which a plurality of first protrusions are positioned on a surface of the conductor, the plurality of first protrusions protruding in a same oblique direction that is oblique to a direction normal to the first face. The electronic device and the electronic module include the above-described wiring board and an electronic component mounted on the wiring board.

